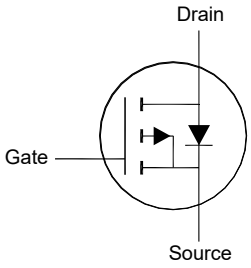
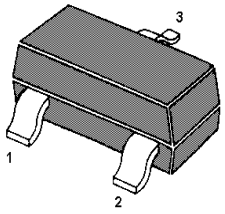
MKA03P110LS-CH

P-Channel Enhancement Mode MOSFET

Features

- AEC-Q101 Qualified
- Surface-mounted package
- Halogen and Antimony Free(HAF), RoHS compliant





1. Gate 2. Source 3. Drain
SOT-23 Plastic Package

Applications

- Portable appliances
- Battery management

Absolute Maximum Ratings(at T_a = 25℃ unless otherwise specified)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$-V_{DS}$	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current		$-I_D$	3.5	A
Pulsed Drain Current [1]		$-I_{DM}$	14	A
Total Power Dissipation [2]	Steady State t ≤ 10 s	P_{tot}	0.6 1.39	W
Operating Junction and Storage Temperature Range		T_j, T_{stg}	- 55 to + 150	℃

Thermal Characteristics

Parameter		Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient [2]	Steady State t ≤ 10 s	$R_{\theta JA}$	208 90	℃/W

[1] Pulse Test: Pulse Width ≤ 100 μs, Duty Cycle ≤ 2%,Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ = 150°C.

[2] Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate

Dated: 20/12/2023 Rev: 01

Characteristics at T_a = 25℃ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at $-I_D$ = 250 µA	$-V_{(BR)DSS}$	30	-	-	V
Zero Gate Voltage Drain Current at $-V_{DS}$ = 24 V	$-I_{DSS}$	-	-	1	µA
Gate-Source Leakage at V_{GS} = ± 20 V	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage at V_{DS} = V_{GS}, $-I_D$ = 250 µA	$-V_{GS(th)}$	1	-	2.5	V
Drain-Source On-State Resistance at $-V_{GS}$ = 10 V, $-I_D$ = 3.5 A at $-V_{GS}$ = 4.5 V, $-I_D$ = 2.5 A	$R_{DS(on)}$	- -	- -	72 110	mΩ
DYNAMIC PARAMETERS					
Forward Transconductance at $-V_{DS}$ = 10 V, $-I_D$ = 2 A	g_{fs}	-	3	-	S
Gate resistance at V_{DS} = 0 V, V_{GS} = 0 V, f = 1 MHz	R_g	-	6	-	Ω
Input Capacitance at $-V_{DS}$ = 20 V, V_{GS} = 0 V, f = 1 MHz	C_{iss}	-	410	-	pF
Output Capacitance at $-V_{DS}$ = 20 V, V_{GS} = 0 V, f = 1 MHz	C_{oss}	-	47	-	pF
Reverse Transfer Capacitance at $-V_{DS}$ = 20 V, V_{GS} = 0 V, f = 1 MHz	C_{rss}	-	40	-	pF
Total Gate Charge at $-V_{DS}$ = 20 V, $-I_D$ = 3 A, $-V_{GS}$ = 10 V at $-V_{DS}$ = 20 V, $-I_D$ = 3 A, $-V_{GS}$ = 4.5 V	Q_g	- -	8.3 4	- -	nC
Gate to Source Charge at $-V_{DS}$ = 20 V, $-I_D$ = 3 A, $-V_{GS}$ = 10 V	Q_{gs}	-	1.8	-	nC
Gate to Drain Charge at $-V_{DS}$ = 20 V, $-I_D$ = 3 A, $-V_{GS}$ = 10 V	Q_{gd}	-	1.5	-	nC
Turn-On Delay Time at $-V_{DD}$ = 20 V, $-V_{GS}$ = 10 V, $-I_D$ = 3 A, R_G = 3.3 Ω	$t_{d(on)}$	-	7.6	-	ns
Turn-On Rise Time at $-V_{DD}$ = 20 V, $-V_{GS}$ = 10 V, $-I_D$ = 3 A, R_G = 3.3 Ω	t_r	-	13	-	ns
Turn-Off Delay Time at $-V_{DD}$ = 20 V, $-V_{GS}$ = 10 V, $-I_D$ = 3 A, R_G = 3.3 Ω	$t_{d(off)}$	-	9.6	-	ns
Turn-Off Fall Time at $-V_{DD}$ = 20 V, $-V_{GS}$ = 10 V, $-I_D$ = 3 A, R_G = 3.3 Ω	t_f	-	2.8	-	ns
Body-Diode PARAMETERS					
Body Diode Voltage at $-I_S$ = 1 A	$-V_{SD}$	-	-	1.2	V
Body-Diode Continuous Current	$-I_S$	-	-	3.5	A
Body Diode Reverse Recovery Time at $-I_S$ = 3 A, di/dt = 100 A / µs	t_{rr}	-	9	-	ns
Body Diode Reverse Recovery Charge at $-I_S$ = 3 A, di/dt = 100 A / µs	Q_{rr}	-	5	-	nC

Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

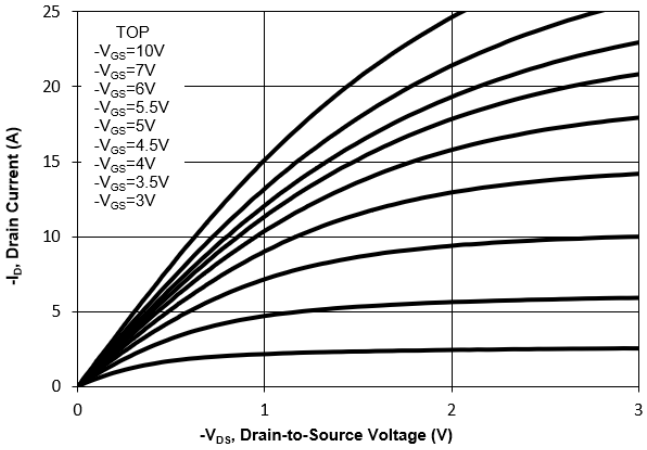


Fig. 2 Typical Transfer Characteristics

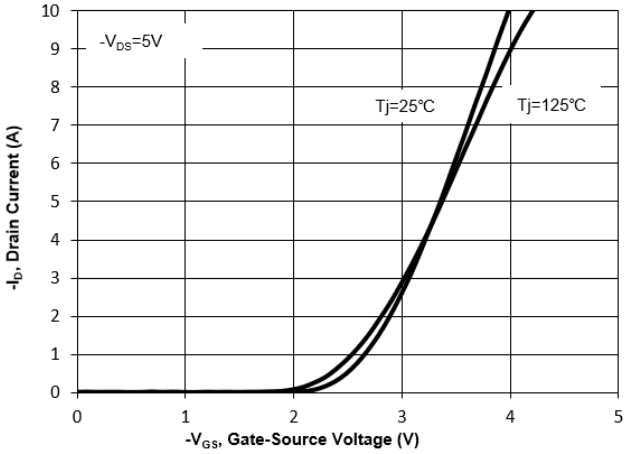


Fig. 3 on-Resistance vs. Drain Current

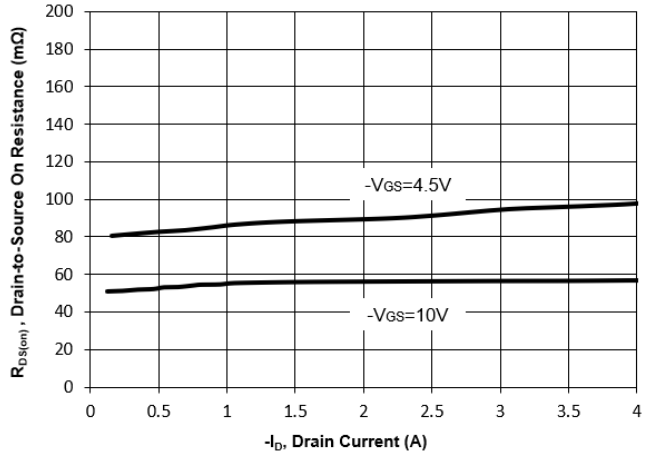


Fig. 4 On-Resistance vs. Gate-Source Voltage

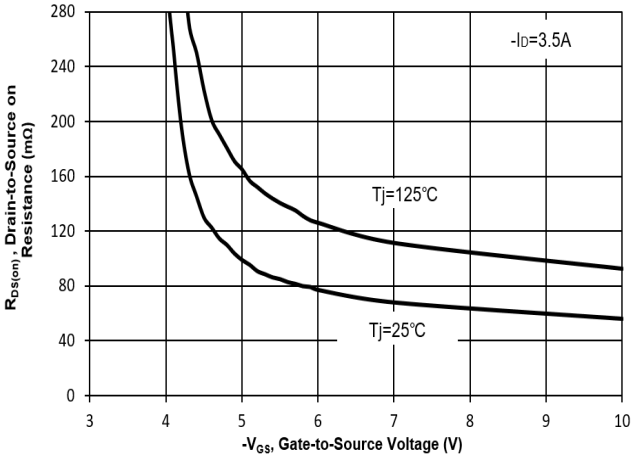


Fig. 5 on-Resistance vs.T_j

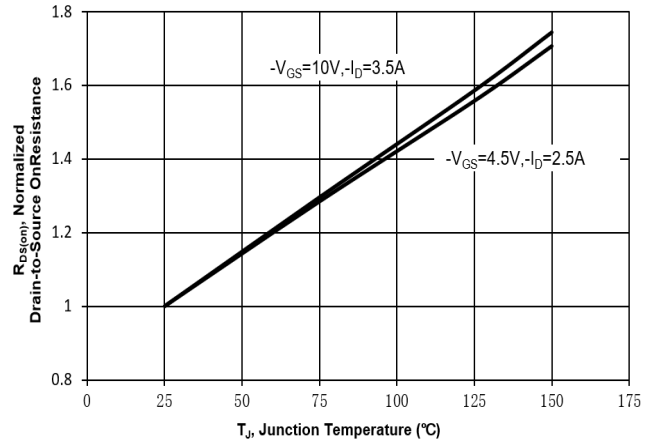
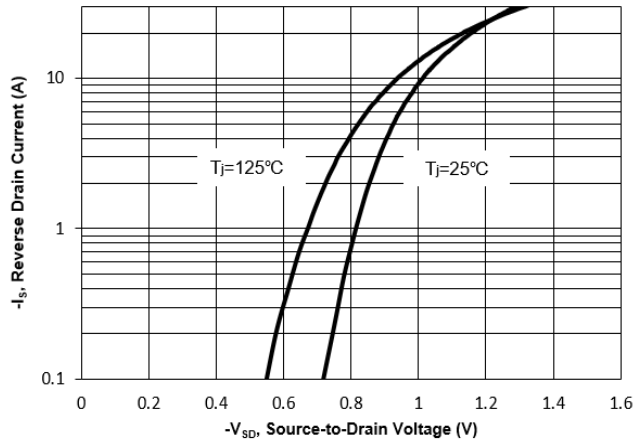


Fig. 6 Typical Forward Characteristics



Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

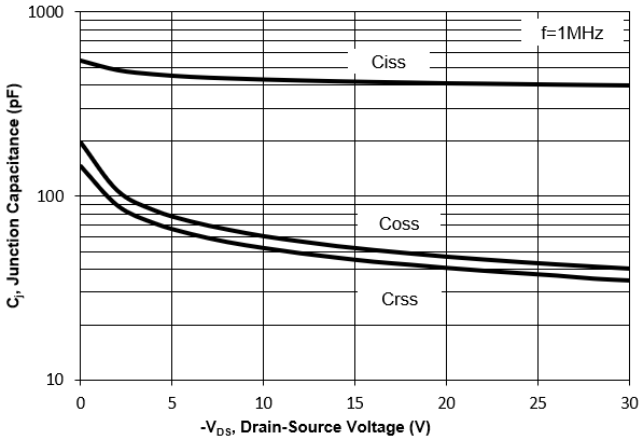


Fig. 8 Drain-Source Leakage Current vs. T_j

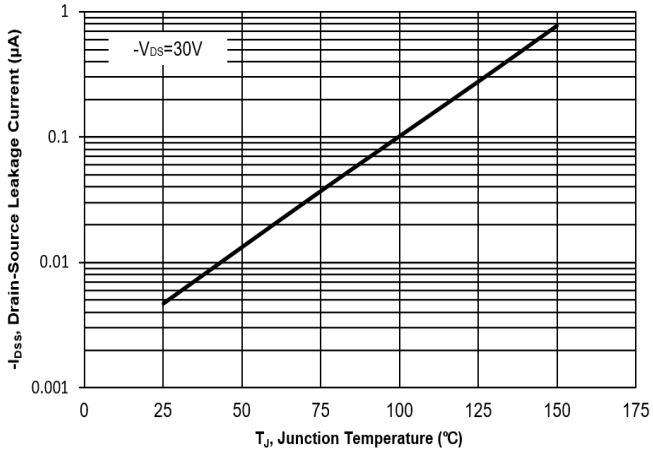


Fig. 9 $V_{(BR)DSS}$ vs. Junction Temperature

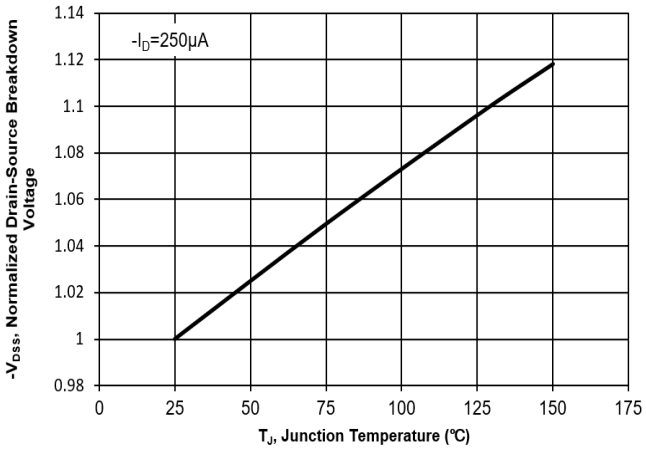


Fig. 10 Gate Threshold Variation vs. T_j

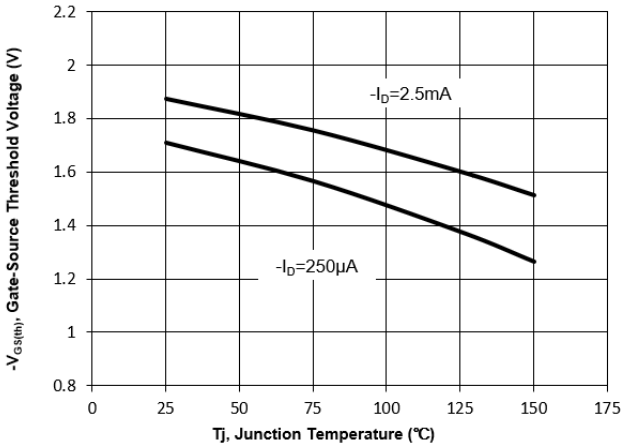
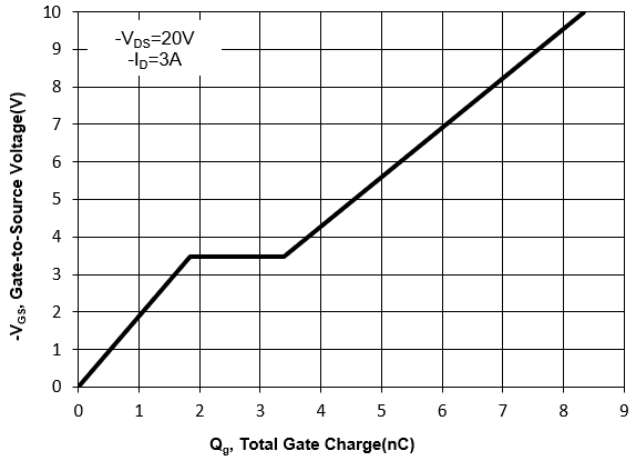


Fig. 11 Gate Charge



Test Circuits

Fig.1-1 Switching times test circuit

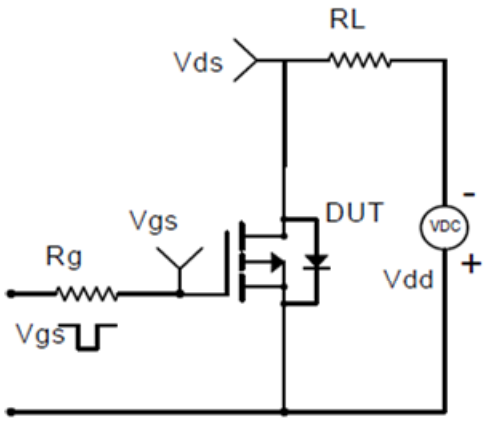


Fig.1-2 Switching Waveform

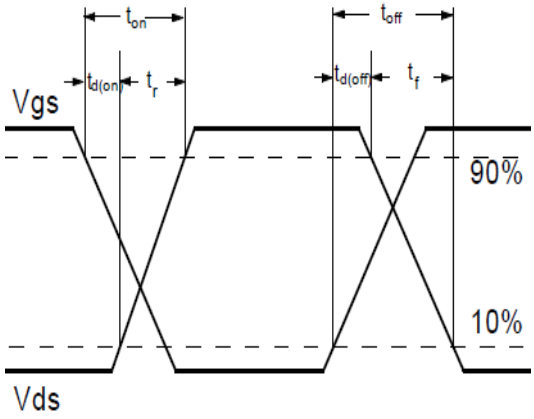


Fig.2-1 Gate charge test circuit

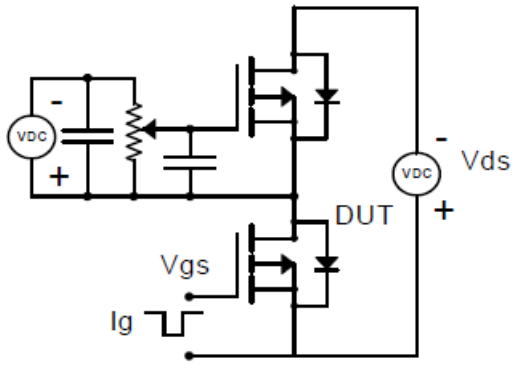
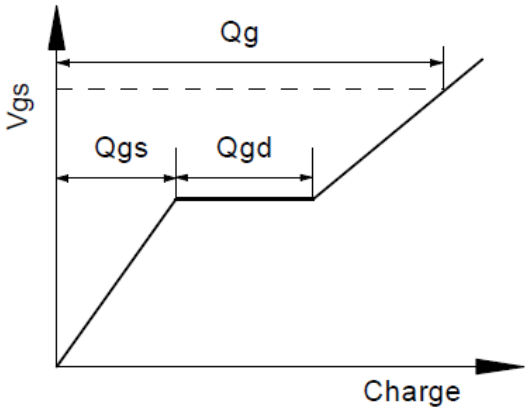


Fig.2-2 Gate charge waveform



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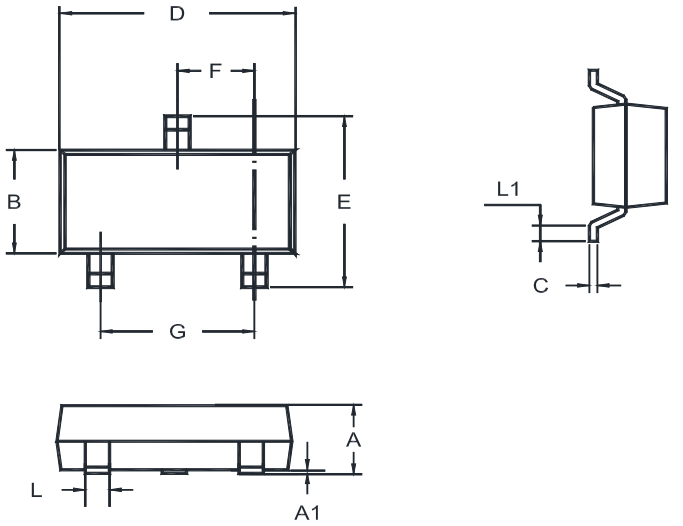
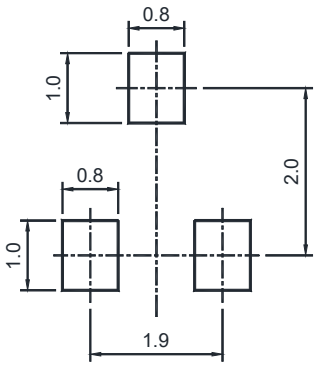
Package Outline (Dimensions in mm) SOT-23



Unit	A	A1	B	C	D	E	F	G	L	L1
mm	1.20 0.89	0.100 0.013	1.40 1.20	0.19 0.08	3.04 2.80	2.6 2.2	1.02 0.89	2.04 1.78	0.51 0.37	0.2 MIN

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-23	8	4 ± 0.1	0.157 ± 0.004	178	7	3,000

Marking information

" P7 " = Part No.

" • " = HAF (Halogen and Antimony Free)

" YM " = Date Code Marking

" Y " = Year

" M " = Month

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